

PCN Number:	20230118000.1	PCN Date:	January 18, 2023
Title:	Qualification of RFAB as an additional Fab site option for select LBC7 devices		
Customer Contact:	PCN Manager	Dept:	Quality Services
Proposed 1st Ship Date:	Apr 18, 2023	Sample requests accepted until:	Feb 18, 2023*

***Sample requests received after February 18, 2023 will not be supported.**

Change Type:

<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Assembly Materials
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification
<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>	Wafer Bump Process
<input checked="" type="checkbox"/>	Wafer Fab Site	<input checked="" type="checkbox"/>	Wafer Fab Materials	<input type="checkbox"/>	Wafer Fab Process
		<input type="checkbox"/>	Part number change		

Notification Details

Description of Change:

Texas Instruments is pleased to announce the qualification of its RFAB fabrication facility as an additional Wafer Fab source for the selected devices listed in the "Product Affected" section.

Current Fab Site			Additional Fab Site		
Current Fab Site	Process	Wafer Diameter	New Fab Site	Process	Wafer Diameter
DP1DM5	LBC7	200 mm	RFAB	LBC7	300 mm

Qual details are provided in the Qual Data Section.

Reason for Change:

Continuity of supply

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Fab Site Information:

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
DP1DM5	DM5	USA	Dallas
RFAB	RFB	USA	Richardson

Sample product shipping label (not actual product label)

Product Affected:

UCC25600D	UCC25600DR
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Qualification Report
Approve Date 26-September-2022

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: UCC25600D	QBS Reference: TPS51604QDSGRQ1	QBS Reference: SN1109009D	QBS Reference: SN65HVD888D
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	3/231/0	-	-
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	3/231/0	3/231/0	3/231/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	3/231/0	3/213/0	3/231/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	3/135/0	-	-
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	-	3/231/0	-
HTOL	B1	Life Test	125C	1000 Hours	-	3/231/0	-	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	3/2400/0	-	-
WBS	C1	Ball Shear	76 balls, 3 units min	Wires	-	-	3/228/0	3/228/0
WBP	C2	Bond Pull	76 Wires, 3 units min	Wires	-	-	3/228/0	3/228/0
PD	C4	Physical Dimensions	Cpk>1.67	-	-	3/30/0	-	-
ESD	E2	ESD CDM	-	250 Volts	1/3/0	-	-	-
ESD	E2	ESD CDM	-	500 Volts	-	1/3/0	-	-
ESD	E2	ESD HBM	-	1000 Volts	1/3/0	-	-	-
ESD	E2	ESD HBM	-	2000 Volts	-	1/3/0	-	-
LU	E4	Latch-Up	Per JESD78	-	1/3/0	-	-	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	3/90/0	-	-

- QBS: Qual By Similarity
- Qual Device UCC25600D is qualified at MSL1 260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the contact below or your local Field Sales Representative.

Location	E-Mail
WW Change Management Team	PCN_ww_admin_team@list.ti.com

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